

# HD74LS06

Hex Inverter Buffers / Drivers  
(with Open Collector High-Voltage Output)

REJ03D0392-0200

Rev.2.00

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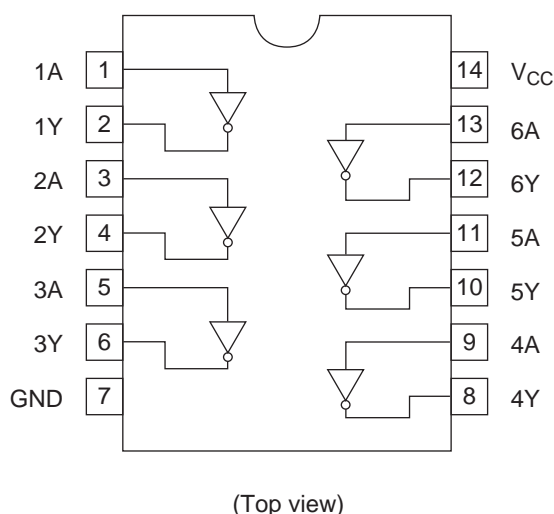
## Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS06P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS06FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS06RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

## Pin Arrangement



## Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	$V_{CC}$ <sup>Note</sup>	7	V
Input voltage	$V_{IN}$	7	V
Output voltage	$V_{OUT}$	30	V
Power dissipation	$P_T$	400	mW
Operating temperature range	$T_{opr}$	-20 to +75	°C
Storage temperature	$T_{stg}$	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

## Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}$	4.75	5.00	5.25	V
Output voltage	$V_{OH}$	—	—	30	V
Output current	$I_{OL}$	—	—	48	mA
Operating temperature	$T_{opr}$	−20	25	75	°C

## Electrical Characteristics

(Ta = −20 to +75 °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	$V_{IH}$	2.0	—	—	V	
	$V_{IL}$	—	—	0.8	V	
Output voltage	$V_{OL}$	—	—	0.4	V	$I_{OL} = 24 \text{ mA}$ $I_{OL} = 48 \text{ mA}$ $V_{CC} = 4.75 \text{ V}, V_{IH} = 2 \text{ V}$
		—	—	0.5		
Input current	$I_{IH}$	—	—	20	μA	$V_{CC} = 5.25 \text{ V}, V_I = 2.7 \text{ V}$
	$I_{IL}$	—	—	−0.4	mA	$V_{CC} = 5.25 \text{ V}, V_I = 0.4 \text{ V}$
	$I_I$	—	—	0.1	mA	$V_{CC} = 5.25 \text{ V}, V_I = 7 \text{ V}$
Output current	$I_{OH}$	—	—	250	μA	$V_{CC} = 4.75 \text{ V}, V_{IL} = 0.8 \text{ V}, V_{OH} = 30 \text{ V}$
Supply current	$I_{CCH}$	—	23	48	mA	$V_{CC} = 5.25 \text{ V}$
	$I_{CCL}$	—	21	51	mA	$V_{CC} = 5.25 \text{ V}$
Input clamp voltage	$V_{IK}$	—	—	−1.5	V	$V_{CC} = 4.75 \text{ V}, I_{IN} = -18 \text{ mA}$

Note: \*  $V_{CC} = 5 \text{ V}, T_a = 25^\circ\text{C}$ 

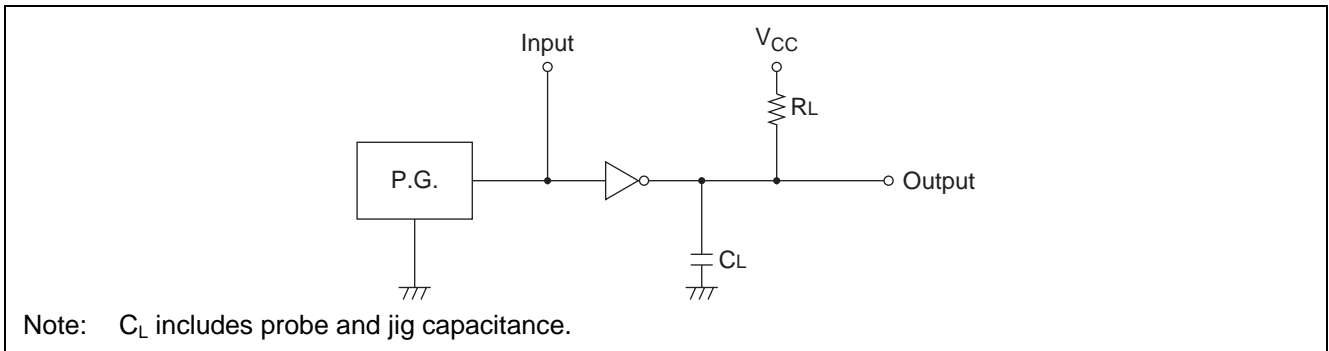
## Switching Characteristics

(V<sub>CC</sub> = 5 V, Ta = 25°C)

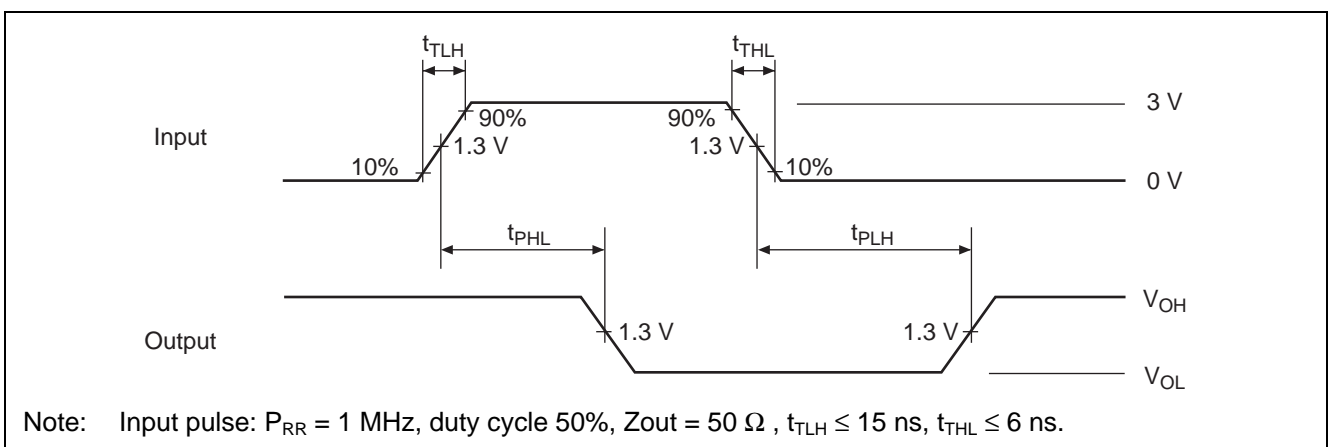
Item	Symbol	min.	typ.	max.	Unit	Condition
Propagation delay time	$t_{PLH}$	—	10	15	ns	$C_L = 15 \text{ pF}, R_L = 110 \Omega$
	$t_{PHL}$	—	15	23	ns	

## Testing Method

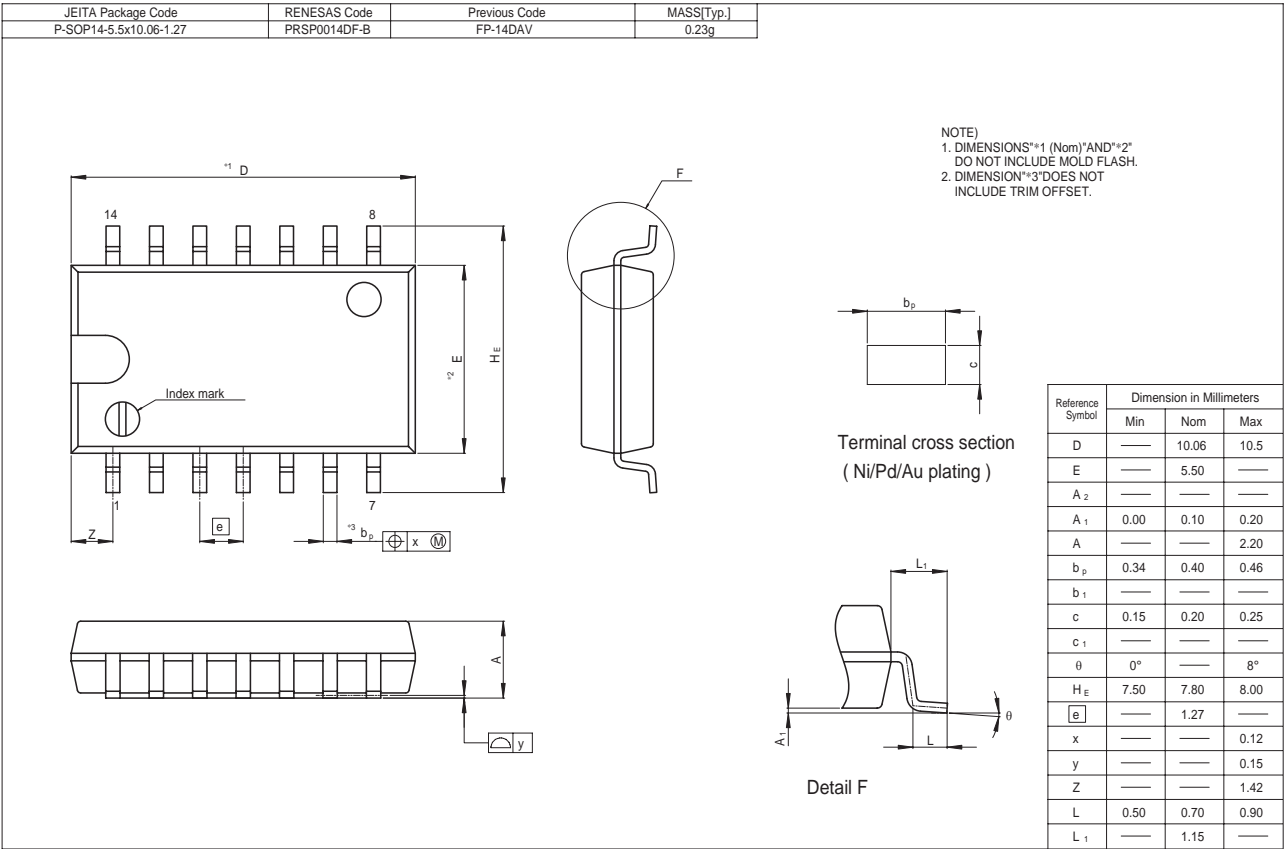
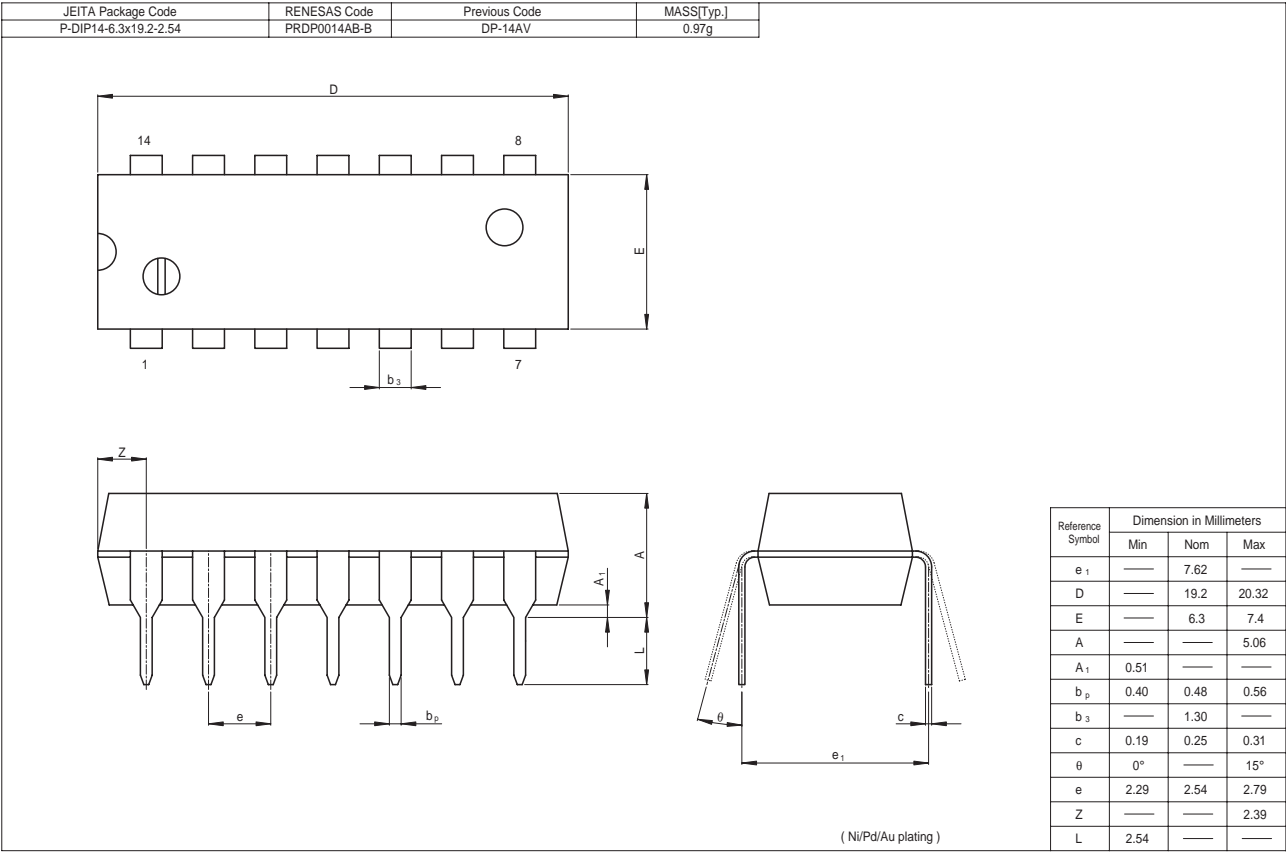
### Test Circuit



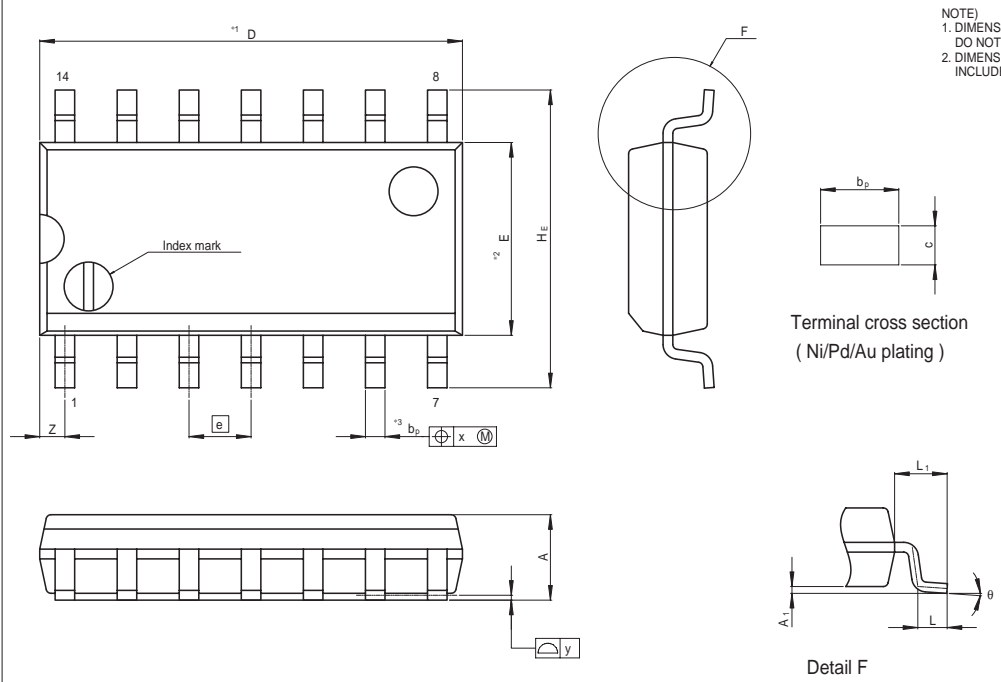
### Waveform



Package Dimensions



JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP14-3.95x8.65-1.27	PRSP0014DE-A	FP-14DNV	0.13g



NOTE)  
1. DIMENSIONS\*1 (Nom)\*AND\*2\*  
DO NOT INCLUDE MOLD FLASH.  
2. DIMENSION\*3\*DOES NOT  
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	8.65	9.05
E	—	3.95	—
A <sub>2</sub>	—	—	—
A <sub>1</sub>	0.10	0.14	0.25
A	—	—	1.75
b <sub>p</sub>	0.34	0.40	0.46
b <sub>1</sub>	—	—	—
c	0.15	0.20	0.25
c <sub>1</sub>	—	—	—
$\theta$	0°	—	8°
H <sub>E</sub>	5.80	6.10	6.20
e	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L <sub>1</sub>	—	1.08	—

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